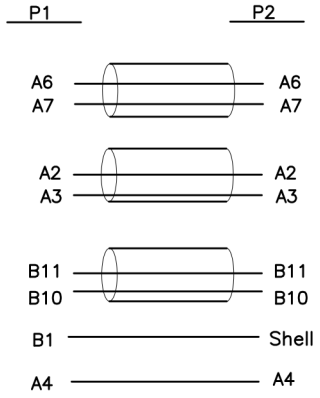


P1

P2

Pin Assignment



NO	DESCRIPTION	Q'TY	UNIT
13	Low pressure molding compound	8	g
12	TYPE C TO PCB~30+24AWG~Clamp	1	pcs
11	Type C~shield~~T=2mm~Primary colors	1	pcs
10	Type C~shield~T=0.2mm~Primary colors	1	pcs
9	CMCF-5m?10G)-SP~PCB+SMT	1	pcs
8	Double conductive copper foil~25u~W=5MM	0.025	m
7	TPE~45P~Black	5	g
6	TPE~65A~Black	8	g
5	UH-SP~Front Cover plate~PC/ABS	1	pcs
4	CM-CF~Shell~PC/ABS	1	pcs
3	TYPE C TO C `30+24AWG`Clamp	1	pcs
2	CMCF-5m(10G)-SP~PCB?+SMT	1	pcs
1	USB3.1~[29AWG(7/0.11TC)+EAM]*2P+[30AWG(7/0.10TC)+A]*1P+24AWG(41/0.08TC)*1C+2EB(16/11/0.08TC 85%)~OD:4.8MM~TPE BLACK	3.08	m

REV.	ECN NO.	DESCRIPTION	DATE	CHANGER

TOLERANCE	INCHES	M/M
.X	.015	.30
.XX	.010	.10
.XXX	.005	.05

DRAWN BY	Leo	CUSTOMER :	
		CUSTOMER NO.:	
CHECK BY		SCALE	NONE
		UNIT	MM
APPD BY		DATE	2021.12.01

TITLE:

DRAWING NO.:

REV. A0

1/1